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 State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power 	SN54LVT16646 WD PACKAGE SN74LVT16646 DGG OR DL PACKAGE (TOP VIEW)							
Dissipation		56] 1 0E						
Members of the Texas Instruments		55 1 1CLKBA						
<i>Widebus</i> ™ Family	1SAB [] 3	54] 1SBA						
Support Mixed-Mode Signal Operation (5-V	GND 4	53 GND						
Input and Output Voltages With 3.3-V V_{CC})	1A1 5	52] 1B1						
 Support Unregulated Battery Operation 	1A2 6	51 0 1B2						
Down to 2.7 V		50 VCC						
 Typical V_{OLP} (Output Ground Bounce) 	1A3 🛛 8	49 1 1B3						
< 0.8 V at V_{CC} = 3.3 V, T_A = 25°C	1A4 🛛 9	48 🛛 1B4						
 ESD Protection Exceeds 2000 V Per 	1A5 🚺 10	47 🛛 1B5						
MIL-STD-883C, Method 3015; Exceeds	GND 🛿 11	46 🛛 GND						
200 V Using Machine Model	1A6 🛛 12	45 🛛 1B6						
(C = 200 pF, R = 0)	1A7 🛛 13	44 🛛 1B7						
 Latch-Up Performance Exceeds 500 mA 	1A8 🛛 14	43 [1B8						
Per JEDEC Standard JESD-17	2A1 🛛 15	42 2B1						
 Bus-Hold Data Inputs Eliminate the Need 	2A2 16	41 2B2						
for External Pullup Resistors	2A3 17	40 2B3						
•	GND 18	39 GND						
Support Live Insertion	2A4 [19	38 2B4 37 2B5						
 Distributed V_{CC} and GND Pin Configuration 	2A5 20 2A6 21	37 U 2B5 36 2B6						
Minimizes High-Speed Switching Noise		36 266 35 V _{CC}						
 Flow-Through Architecture Optimizes 	V _{CC} L 22 2A7 1 23	34 [] 2B7						
PCB Layout	2A7 [23 2A8 [24	33 2B8						
Package Options Include Plastic 300-mil	GND 25	32 GND						
Shrink Small-Outline (DL) and Thin Shrink	2SAB 26	31 2SBA						
Small-Outline (DGG) Packages and 380-mil	2CLKAB 27	30 2CLKBA						
Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings	2DIR [28	29 20E						

description

The 'LVT16646 are 16-bit bus transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'LVT16646.

Output-enable (\overline{OE}) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. The direction control (DIR) determines which bus receives data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data may be stored in one register and/or B data may be stored in the other register.



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SN54LVT16646, SN74LVT16646 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS149C - JULY 1994 - REVISED JULY 1995

description (continued)

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT16646 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

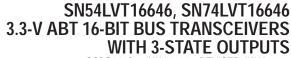
The SN54LVT16646 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74LVT16646 is characterized for operation from -40°C to 85°C.

INPUTS				DATA	A I/Os	OPERATION OR FUNCTION						
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	OFERATION OR FUNCTION				
Х	Х	\uparrow	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified [†]				
Х	Х	Х	\uparrow	Х	Х	Unspecified [†]	Input	Store B, A unspecified [†]				
Н	Х	\uparrow	\uparrow	Х	Х	Input	Input	Store A and B data				
н	Х	H or L	H or L	Х	Х	Input disabled	Input disabled	Isolation, hold storage				
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus				
L	L	Х	H or L	Х	Н	Output	Input	Stored B data to A bus				
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus				
L	Н	H or L	Х	Н	Х	Input	Output	Stored A data to B bus				

ELINCTION TABLE

[†] The data output functions may be enabled or disabled by various signals at OE and DIR. Data input functions are always enabled; i.e., data at the bus pins will be stored on every low-to-high transition of the clock inputs.





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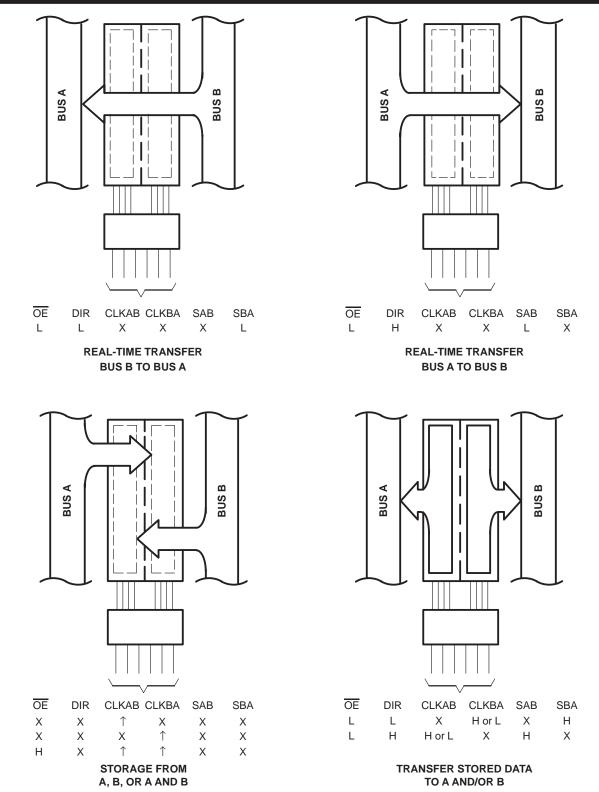
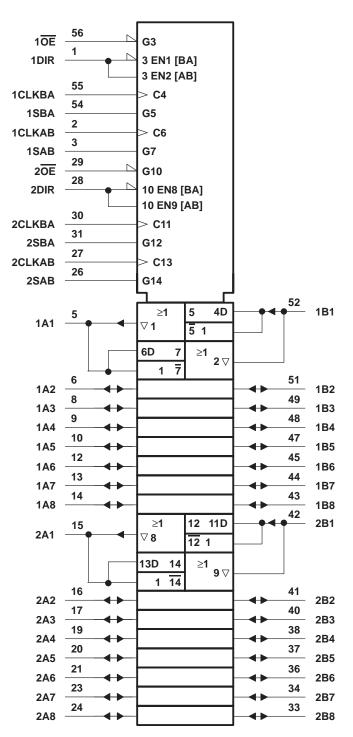


Figure 1. Bus-Management Functions



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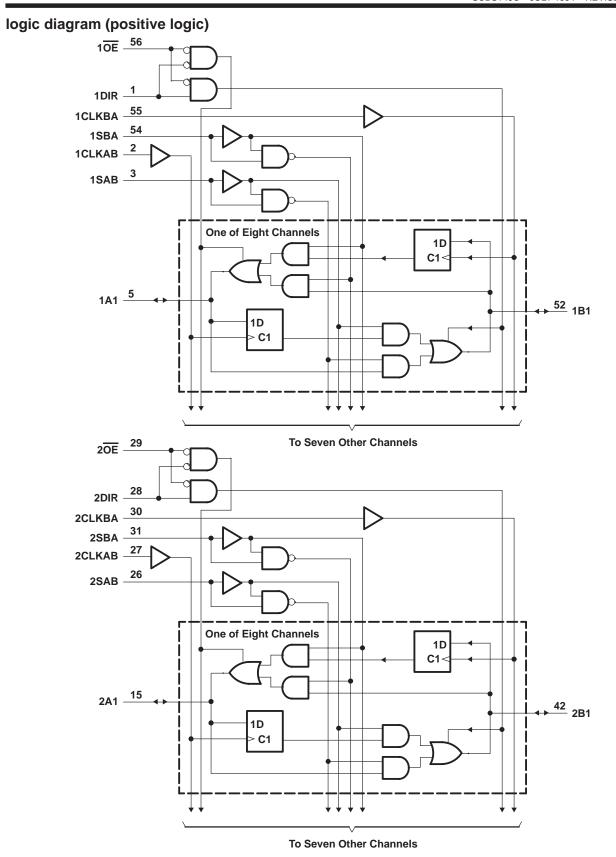
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} 0 Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high state or power-off state, V_{O} (see Note 1) –	
Current into any output in the low state, I_{O} : SN54LVT16646	
SN74LVT16646	
Current into any output in the high state, I _O (see Note 2): SN54LVT16646	
SN74LVT16646	
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I_{OK} ($V_{O} < 0$)	
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DGG package	
DL package	1.4 W
Storage temperature range, T _{stg} –65	5°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

This current flows only when the output is in the high state and $V_O > V_{CC}$. 2.

The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. 3. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

recommended operating conditions (see Note 4)

			SN54LV	T16646	SN74LV	UNIT		
			MIN	MAX	MIN	MAX	UNIT	
Vcc	Supply voltage	upply voltage						
VIH	High-level input voltage	2	EM	2		V		
VIL	Low-level input voltage		0.8		0.8	V		
VI	Input voltage		5.5		5.5	V		
ЮН	High-level output current		Č,	-24		-32	mA	
IOL	Low-level output current		201	48		64	mA	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	PP C	10		10	ns/V	
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	_			SNS	54LVT16	646	SN7	646		
PARAMETER	'	EST CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
VIK	V _{CC} = 2.7 V,	lj = -18 mA				-1.2			-1.2	V
	$V_{CC} = MIN \text{ to } MAX^{\ddagger},$	I _{OH} = -100 μA		V _{CC} -0).2		V _{CC} -0	.2		
Ver	V _{CC} = 2.7 V,	I _{OH} = - 8 mA		2.4			2.4	2.4		
∨он	V _{CC} = 3 V	I _{OH} = – 24 mA		2						V
	VCC = 3 V	$I_{OH} = -32 \text{ mA}$					2			
	$\lambda = 2.7 \lambda$	I _{OL} = 100 μA				0.2			0.2	
	$V_{CC} = 2.7 V$	I _{OL} = 24 mA				0.5			0.5	
		I _{OL} = 16 mA				0.4	0.4			V
VOL	$V_{CC} = 3 V$	I _{OL} = 32 mA			0.5					
	vCC = 2 v	I _{OL} = 48 mA			0.55					
		I _{OL} = 64 mA		M			0.55			
	V _{CC} = 3.6 V,	$V_I = V_{CC} \text{ or } GND$	Control inputs			±1			±1	
	$V_{CC} = 0 \text{ or MAX}^{\ddagger},$	V _I = 5.5 V	Control inputs	<u></u> 10			10			
Ц	V _{CC} = 3.6 V	V _I = 5.5 V			6	20			20	μA
		VI = VCC	A or B ports§	5			5			
		$V_{I} = 0$]	4	2	-10	-		-10	
loff	$V_{CC} = 0,$	V_{I} or $V_{O} = 0$ to 4.5	5 V	Y					±100	μA
ha sa	$V_{CC} = 3 V$	V _I = 0.8 V	A or B ports	75			75			۸
l(hold)	vCC = 2 v	V _I = 2 V	A OF B POILS	-75			-75			μA
IOZH	V _{CC} = 3.6 V,	VO = 3 V				1			1	μA
IOZL	V _{CC} = 3.6 V,	$V_{O} = 0.5 V$	_			-1			-1	μA
lee			Outputs high			0.12			0.12	
	$V_{CC} = 3.6 V,$ $V_{I} = V_{CC} \text{ or GND}$	I _O = 0,	Outputs low	5		5		5	mA	
			Outputs disabled	0.12			0.12			
∆I _{CC} ¶		$C_{C} = 3 \text{ V to } 3.6 \text{ V},$ One input at $V_{CC} - 0.6 \text{ V},$ her inputs at V_{CC} or GND				0.2			0.2	mA
Ci	V _I = 3 V or 0				3.5			3.5		pF
C _{io}	V _O = 3 V or 0				12			12		pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. [‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. [§] Unused pins at V_{CC} or GND

I This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

					T16646			SN74LV	T16646		
			V _{CC} = ± 0.3	3.3 V 3 V	V _{CC} =	2.7 V	= ۷ _{CC} ± 0.	3.3 V 3 V	V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	150	50	150	0	150	0	150	MHz
t _W	Pulse duration, CLK high or low		3.3		3.3		3.3		3.3		ns
+	Setup time,	Data high	1.3	ŀ	1.4		1.3		1.4		ns
t _{su}	SU A or B before CLKAB↑ or CLKBA↑	Data low	2.4	201	3		2.4		3		115
1 +.	Hold time,	Data high	0.5	20	0		0.5		0		20
	A or B after CLKAB↑ or CLKBA↑	Data low	0.6	Q	0.5		0.5		0.5		ns

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

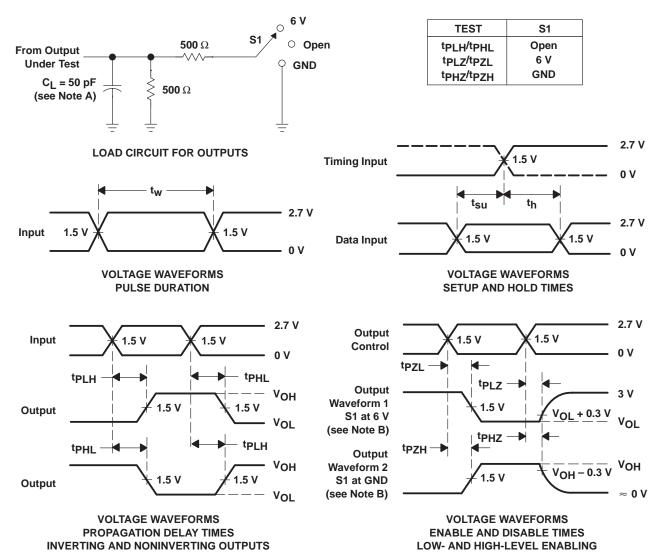
				SN54LV	T16646			SN7	4LVT16	646		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.		V _{CC} =	2.7 V		CC = 3.3 ± 0.3 V	V	V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX	
f _{max}			150				150					MHz
^t PLH	CLKBA or	A or B	1.8	6		6.9	1.8	3.8	5.7		6.7	ns
^t PHL	CLKAB	AOIB	2.1	5.9		6.6	2.1	3.9	5.7		6.5	115
^t PLH	A or B	B or A	1.3	4.9	4	5.6	1.3	3	4.7		5.4	ns
^t PHL	AUB	BUIA	1	4.8	ME	5.8	1	3.1	4.7		5.6	115
^t PLH	SBA or SAB‡	A or B	1.4	6.4	P.F	7.4	1.4	4	6.2		7.2	ns
^t PHL	SDA UI SAD+	AUB	1.4	6.4	L.K	7.4	1.4	4.3	6.2		7.2	115
^t PZH	OE	A or B	1	5.7		7.4	1	3	5.4		6.4	ns
^t PZL	UE	AOIB	1	6.5		7.5	1	3.1	5.6		6.5	115
^t PHZ	OE	A or B	2.3	6.7		7.1	2.3	4.6	6.5		6.9	ns
^t PLZ	UE	AOID	2.2	6		6.5	2.2	4.5	5.8		5.9	115
^t PZH	DIR	A or B	1	5.9		7.7	1	3.3	5.7		6.7	ns
^t PZL	DIK	AUID	1.2	5.9		7.3	1.2	3.5	5.8		6.7	115
^t PHZ	DIR	A or B	1.7	7.3		8.5	1.7	4.7	7.2		8.3	ns
^t PLZ	DIR	AUB	1.5	7.8		7.4	1.5	4.9	6.6		7.2	115

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡]These parameters are measured with the internal output state of the storage register opposite to that of the bus input.



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



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